

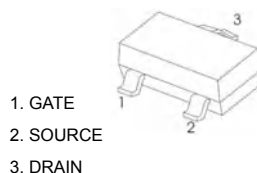
FEATURES

- High density cell design for low $R_{DS(ON)}$
- Voltage controlled small signal switch
- Rugged and reliable
- High saturation current capability

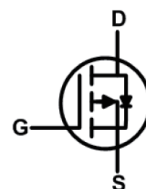
V_{DS} -20 V
 I_D -3.0 A
 $R_{DS(ON)}$ 55 m Ω

A1SHB

SOT-23



Equivalent Circuit



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Maximum ratings ($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 12	
Continuous Drain Current	I_D	-3	A
Pulsed Drain Current	I_{DM}	-10	
Continuous Source-Drain Diode Current	I_S	-0.72	
Maximum Power Dissipation	P_D	1.2	W
Thermal Resistance from Junction to Ambient($t \leq 5s$)	$R_{\theta JA}$	357	$^\circ\text{C}/\text{W}$
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{stg}	-55 ~ +150	

Electrical characteristics (T_a=25°C unless otherwise noted)

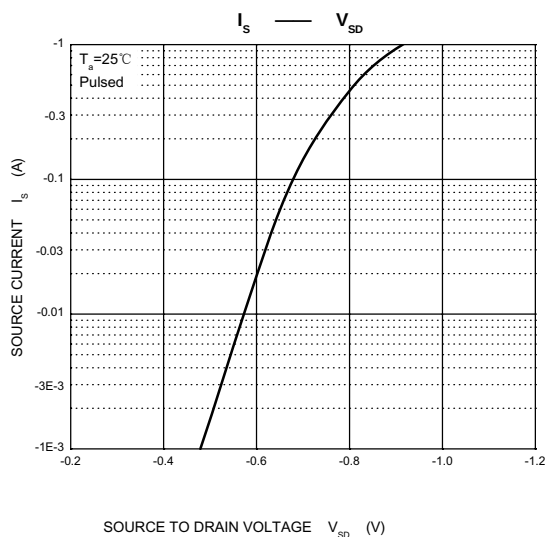
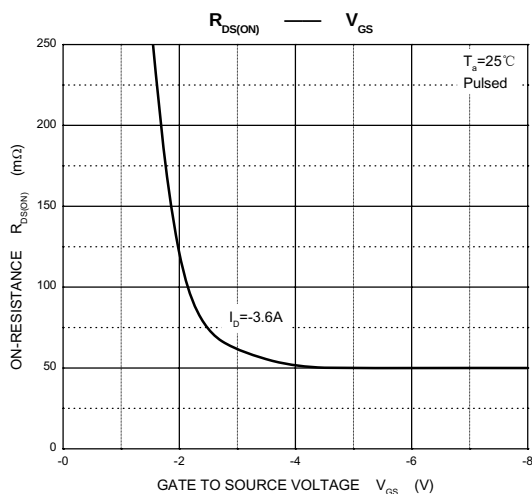
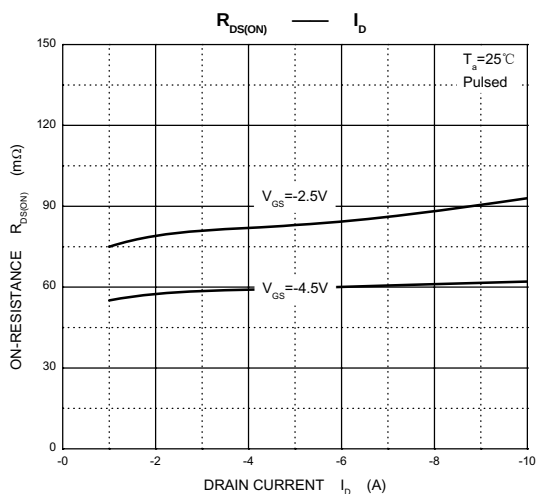
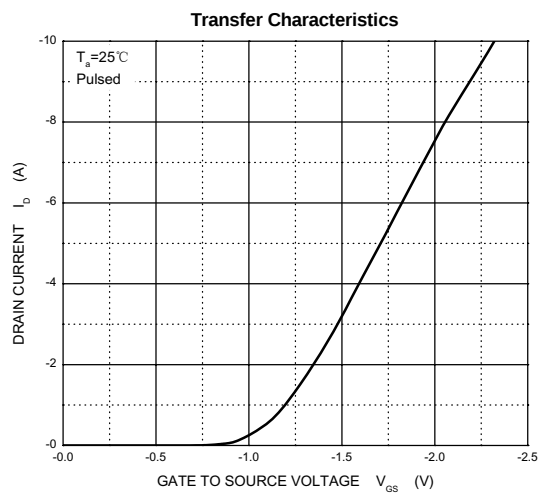
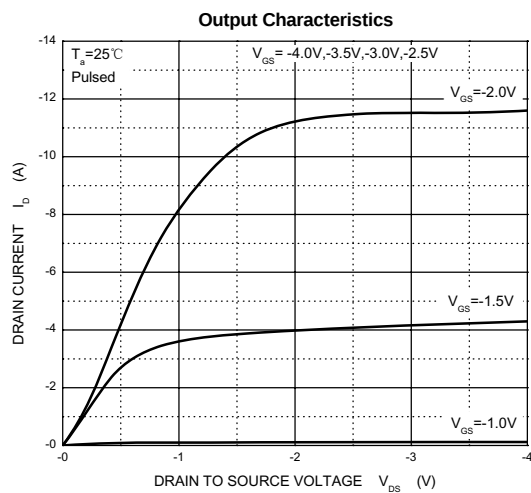
Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Static						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D =-250μA	-20			V
Gate-source threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250μA	-0.4		-1	
Gate-source leakage	I _{GSS}	V _{DS} =0V, V _{GS} =±8V			±100	nA
Zero gate voltage drain current	I _{DSS}	V _{DS} =-20V, V _{GS} =0V			-1	μA
Drain-source on-state resistance ^a	R _{DS(on)}	V _{GS} =-4.5V, I _D =-3A		0.055	0.080	Ω
		V _{GS} =-2.5V, I _D =-2.0A		0.080	0.122	
Forward transconductance ^a	g _{fs}	V _{DS} =-5V, I _D =-3A		6.5		S
Dynamic ^b						
Input capacitance	C _{iss}	V _{DS} =-10V,V _{GS} =0V,f =1MHz		405		pF
Output capacitance	C _{oss}			75		
Reverse transfer capacitance	C _{rss}			55		
Total gate charge	Q _g	V _{DS} =-10V,V _{GS} =-4.5V,I _D =-3A		5.5	10	nC
		V _{DS} =-10V,V _{GS} =-2.5V,I _D =-3A		3.3	6	
Gate-source charge	Q _{gs}			0.7		
Gate-drain charge	Q _{gd}			1.3		
Gate resistance	R _g	f =1MHz		6.0		Ω
Turn-on delay time	t _{d(on)}	V _{DD} =-10V, R _L =10Ω, I _D =-1A, V _{GEN} =-4.5V,R _g =1Ω		11	20	ns
Rise time	t _r			35	60	
Turn-off delay time	t _{d(off)}			30	50	
Fall time	t _f			10	20	
Drain-source body diode characteristics						
Continuous source-drain diode current	I _S	T _C =25°C			-1.3	A
Pulse diode forward current ^a	I _{SM}				-10	
Body diode voltage	V _{SD}	I _S =-0.7A		-0.8	-1.2	V

Notes :

a. Pulse Test : Pulse Width < 300μs, Duty Cycle ≤ 2%.

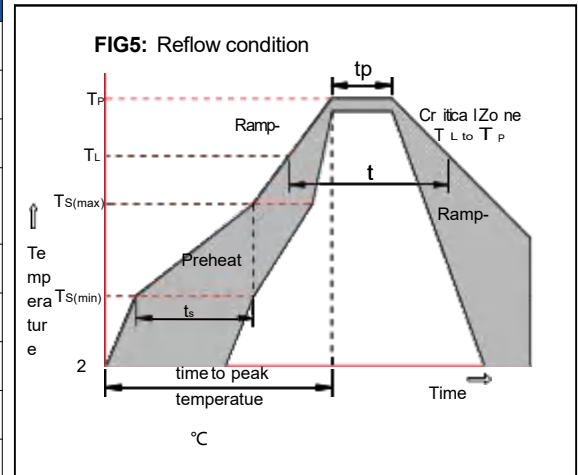
b. Guaranteed by design, not subject to production testing.

RATING AND CHARACTERISTIC CURVES



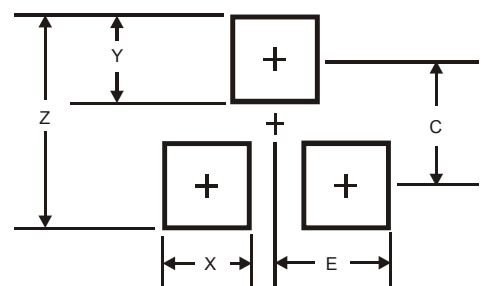
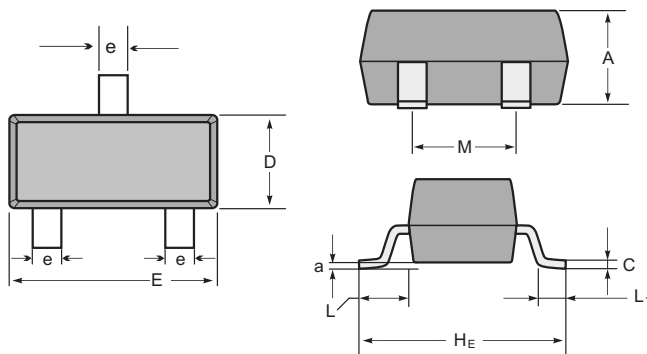
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_P)		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260°C



Package Dimensions & Suggested Pad Layout

SOT23



SOT-23 mechanical data

UNIT	A	C	D	E	HE	e	M	L	L1	a
mm	max	1.1	0.15	1.4	3.0	2.6	0.5	1.95	0.55 (ref)	0.36 (ref)
	min	0.9	0.08	1.2	2.8	2.2	0.3	1.7		0.15
mil	max	43	6	55	118	102	20	77	22 (ref)	14 (ref)
	min	35	3	47	110	87	12	67		6

Dimensions	SOT23
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35

